



Product Change Notification

109014 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 109014 - 00
Change Title: All Intel® Components, PCN 109014-00, Label, Intel Shelf Life Extension, Moisture Label in Compliance with JEDEC JEP113 “Symbol and Labels for Moisture-Sensitive Devices”, Addition of Embossed Batch Number and Bottom Seal (from 2 -Sided to 3 -Sided)
Date of Publication: April 17, 2009

Key Characteristics of the Change:

Moisture Label
Shelf Life Extension
Embossed (MBB Manufacture’s) Batch Number
2-Sided to 3-Sided Sealed Edge

Forecasted Key Milestones:

	All Products
Date Customer Must be Ready to Receive Post-Conversion Material:	May 18, 2009

Description of Change to the Customer:

In order to conform to industry standards Intel is updating the moisture barrier bag (MBB) label to JEDEC JEP113 compliant moisture-sensitive labeling. Additionally, Intel will start to use a new MBB. The new MBB is sealed on 3 edges, and will have the MBB Manufacturer’s batch number embossed on the bottom edge, to enhance traceability.


Please see examples of the current and new labels shown below.

Shelf Life Policy


This change allows Intel to extend the shelf life of these products to thirty months for moisture sensitive products not to exceed 60 months with a refresh following JEDEC Std-033 “Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices”, while maintaining compliancy to JEDEC Std-020 “Joint IPC/JEDEC Standard For Moisture/Reflow Sensitivity Classification for nonhermetic solid state surface-mount devices”. Non-moisture sensitive product shelf life will also be extended to 60 months.

Intel will continue to provide customers with 6 months shelf life upon receipt of product, as referenced in the Intel® Packaging Information Packaging Databook.

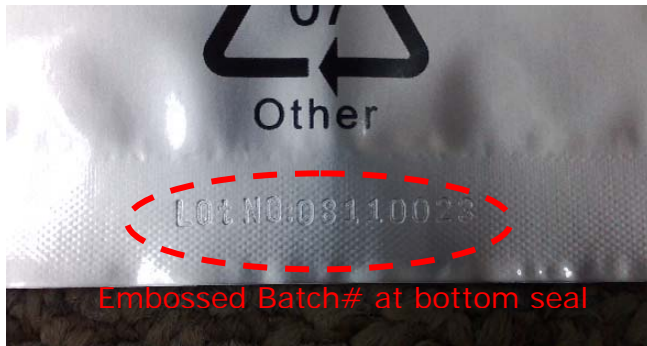
Current Caution Label:

	CAUTION	LEVEL
	This bag contains MOISTURE-SENSITIVE DEVICES	
		<input type="checkbox"/>
		<small>If Blank, see adjacent bar code label</small>
<ol style="list-style-type: none"> 1. Calculated shelf life in sealed bag: 12 months at < 40 °C and < 90% relative humidity (RH) 2. Peak package body temperature: _____ °C <small>If Blank, see adjacent bar code label</small> 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must <ol style="list-style-type: none"> a) Mounted within: _____ hours of factory conditions <small>If Blank, see adjacent bar code label</small> b) stored at <10% RH 4. Devices require bake, before mounting, if: <ol style="list-style-type: none"> a) Humidity Indicator Card is > 10% when read at 23 ± 5 °C b) 3a or 3b not met. 5. If baking is required, devices may be baked for 48 hours at 125 ± 5 °C <p>Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure</p> <p>Bag Seal Date: _____ <small>If Blank, see adjacent bar code label</small></p> <p>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</p>		

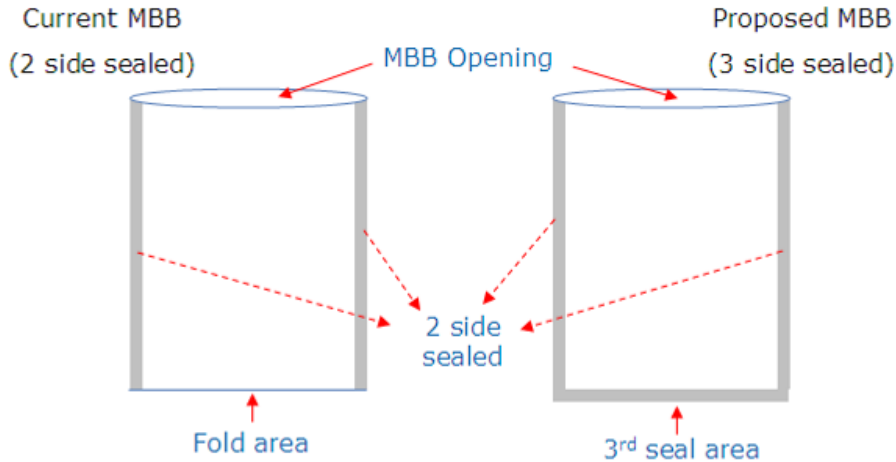
New Caution Label:

	Caution	LEVEL
	This bag contains MOISTURE-SENSITIVE DEVICES	
		<input type="checkbox"/>
		<small>If blank, see adjacent bar code label</small>
<ol style="list-style-type: none"> 1. Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH) 2. Peak package body temperature: _____ °C <small>If blank, see adjacent bar code label</small> 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be <ol style="list-style-type: none"> a) Mounted within: _____ hours of factory conditions <small>If blank, see adjacent bar code label</small> b) Stored per J-STD-033 4. Devices require bake, before mounting, if: <ol style="list-style-type: none"> a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23 ± 5 °C b) 3a or 3b are not met 5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure <p>Bag Seal Date: _____ <small>If blank, see adjacent bar code label</small></p> <p>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</p>		

MBB Manufacture's Embossed Batch#



(3-side sealed (adding bottom seal))



Customer Impact of Change and Recommended Action:

The impact of the change is outlined in the **Current** and **To Be** table listed below. All standard terms and conditions apply. Customers may receive a mix of "current" and "to be" bags and labels until the current inventory is depleted.

Current	To Be
Moisture label not aligned to JEDEC JEP113 standard	Label alignment with JEDEC JEP113 on moisture barrier bags
Two sided seal open bag with a fold and no embossed batch number	Three sided seal open bag and an embossed batch number at bottom seal – Moisture Barrier Bag (MBB) manufacturer's batch number
Test Lot Date greater than 12 months is considered aged	Bag seal date greater than 30 months total considered aged for Moisture Sensitive Product and test lot date greater than 60 months total for Non-Moisture Sensitive Products
Requires acknowledgment by the customer to receive shipment for material older than 12 months	Intel will only require waivers for moisture sensitive product older than 24 months or 54 months for non-moisture sensitive products from the effective date to continue to provide a 6 months customer shelf life

Products Affected / Intel Ordering Codes:

All Intel® Component Desiccant Packed Products

Reference Documents / Attachments:

Document:

JEDEC Standards Home Page
 Intel® Packaging Information Packaging Databook

Location #:

<http://www.jedec.org/>
<http://www.intel.com/design/packtech/packbook.htm>

PCN Revision History:

Date of Revision:

April 17, 2009

Revision Number:

00

Reason:

Originally Published PCN